

What is claimed is:

1. A method of providing cargo security, comprising:
  - providing a closure system that includes a memory module and a locking module, wherein the memory module is fixed to the locking module;
  - loading into the memory module information corresponding to an enclosure; and
  - locking the enclosure with the locking module.
2. The method of claim 1, wherein loading into the memory module information corresponding to the enclosure includes loading a manifest for the enclosure.
3. The method of claim 1, wherein loading into the memory module information corresponding to the enclosure includes loading a digital image of contents of the enclosure.
4. The method of claim 1, wherein loading into the memory module information corresponding to the enclosure includes loading a locking signature.
5. The method of claim 4, wherein the locking signature includes when the enclosure was unlocked.

6. The method of claim 4, wherein the locking signature includes who unlocked the enclosure.

7. The method of claim 4, wherein the locking signature includes where the enclosure was unlocked.

8. The method of claim 1, further comprising reading from the memory module the information corresponding to the enclosure while the locking module is locking the enclosure.

9. A closure system, comprising:  
a locking module configured to selectively prevent unpermitted access to an enclosure; and  
a memory module correlated to the locking module and configured to store information corresponding to the enclosure.

10. The closure system of claim 9, wherein the memory module is correlated to the locking module via a common identifier.

11. The closure system of claim 9, wherein the memory module is correlated to the locking module via physical coupling.

12. A closure system, comprising:
  - a locking module configured to selectively prevent unpermitted access to an enclosure; and
  - a memory module coupled to the locking module and configured to store information corresponding to the enclosure.
13. The closure system of claim 12, wherein the memory module is permanently coupled to the locking module.
14. The closure system of claim 13, wherein the memory module is embedded in the locking module.
15. The closure system of claim 13, wherein the memory module is glued to the locking module.
16. The closure system of claim 13, wherein the locking module defines a bore holding a potting material, and wherein the memory module is set in the potting material.
17. The closure system of claim 12, wherein the locking module includes a keying mechanism configured to selectively provide access to the enclosure.

18. The closure system of claim 12, wherein the locking module includes a locking bar.

19. The closure system of claim 12, wherein the locking module includes a locking cable.

20. The closure system of claim 12, wherein the locking module includes a locking seal.

21. The closure system of claim 12, wherein the locking module includes a padlock.

22. The closure system of claim 12, wherein the memory module includes a nonvolatile memory.

23. The closure system of claim 12, wherein the memory module digitally stores information corresponding to the enclosure.

24. The closure system of claim 12, wherein the memory module stores a manifest for the enclosure.

25. The closure system of claim 12, wherein the memory module stores a digital image of contents of the enclosure.

26. The closure system of claim 12, wherein the memory module stores a locking signature.

27. The closure system of claim 26, wherein the locking signature includes when the enclosure was unlocked.

28. The closure system of claim 26, wherein the locking signature includes who unlocked the enclosure.

29. The closure system of claim 26, wherein the locking signature includes where the enclosure was unlocked.

30. The closure system of claim 12, wherein the enclosure is a freight container.

31. The closure system of claim 12, wherein the memory module includes an interface having a plurality of electrically conductive contact surfaces.

32. The closure system of claim 31, wherein the contact surfaces are concentrically arranged.

33. The closure system of claim 31, wherein the memory module is configured to be selectively powered via the contact surfaces.

34. The closure system of claim 31, wherein the memory module includes clock and data pins, and wherein the contact surfaces are electrically coupled to the clock and data pins.

35. The closure system of claim 34, wherein the memory module is configured to be selectively powered via the clock and data pins.

36. The closure system of claim 12, further comprising a cap configured to cover the memory module.

37. The closure system of claim 36, wherein the cap is secured to the locking module via a leash.

38. A closure system, comprising:
- a locking module configured to selectively prevent access to an enclosure, wherein the locking module includes a body defining an internal bore;
- a nonvolatile memory device;
- a generally planar circuit board having a first side with a plurality of electrically conductive contact surfaces, and a second side which mounts the nonvolatile memory device in a determined electrical relation with the contact surfaces;
- wherein the circuit board and the nonvolatile memory device are installed within the internal bore such that the contact surfaces are substantially exposed for electrical access of the nonvolatile memory device.
39. The closure system of claim 38, wherein the contact surfaces are concentrically arranged.
40. The closure system of claim 38, wherein the nonvolatile memory device is selectively powered via the contact surfaces.
41. The closure system of claim 38, wherein the contact surfaces connect to clock and data pins of the nonvolatile memory device.

42. The closure system of claim 41, wherein the nonvolatile memory device is selectively powered via clock and data input lines.

43. The closure system of claim 38, wherein the bore holds a potting material, the second side of the circuit board being set in the potting material.

44. The closure system of claim 38, further comprising a cap configured to cover the circuit board.